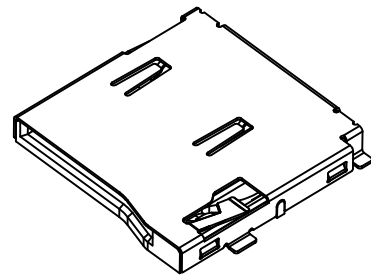
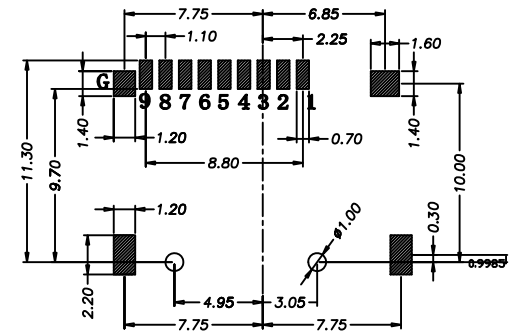
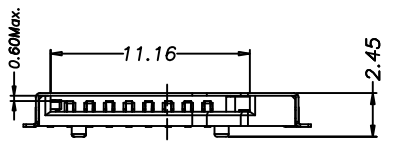
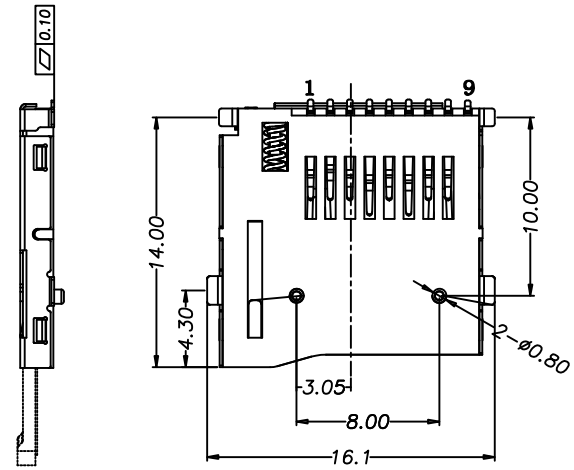
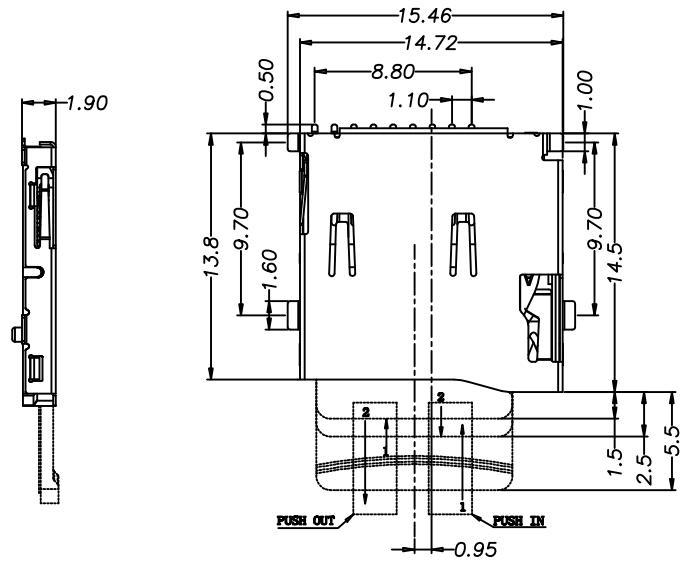


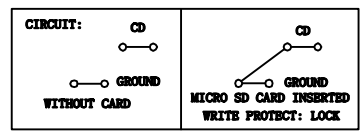
更改 REV	变更记录 MODIFICATION
A	ECXXXXX



- 1. Material/Plated**
- 1.1 Housing: LCP E471i, Black UL 94V-0.
 - 1.2 Cam: LCP, Black UL 94V-0.
 - 1.3 Terminal: Copper Alloy C5210R, 10u" Gold Plated At Contact Area, Tin 100u" Plated At Soldered Area, Nickel 40u" Underplated Overall
 - 1.4 Shell: Stainless steel SUS304, Nickel 40u" plated and gold 1u" plated on solder pad
 - 1.5 Spring: SWB
 - 1.6 Cam Pin: Stainless steel
- 2. Electrical Performance**
- 2.1 Rated Voltage: 100V DC Max.
 - 2.2 Rated Current: 0.5A DC Max.
 - 2.3 Contact Resistance: 100mΩ Max.
 - 2.4 Insulation Resistance: 100MΩ Min.
 - 2.5 Dielectric Strength: 500V AC
- 3. Mechanical Performance**
- 3.1 Insertion Force: 15N Max.
 - 3.2 Pulling Force: 1-10N
 - 3.3 Durability: 10000 Cycles
 - 4. Operating Temperature: -25° C To +85° C



Pin NO.	Name
1	DAT2:Data Line
2	CD/DAT3:Card Detect/Line
3	CMD:Command Response
4	VDD:Supply Voltage
5	CLK:Clock
6	VSS:Supply Voltage Ground
7	DAT0:Data Line
8	DAT1 ² :Data Line
9	CD:Card Detection
G	G:Ground



P. C. B LAYOUT (Tolerance: ±0.05)

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5°	名 称(TITLE) Micro SD PUSH 10u' 正贴	
.X± 0.30	.X*± 2°		
.XX± 0.20	.XX*± 1°		
材 质(MATERIAL)	料 号(PART NO.)	图 号(DWG NO.)	
M	7MSDP-BA-1016	7MSDP-BA-1016	
审 核(APPROVAL)	核 对(CHECKED)	製 图(DRAWN)	比 例 SCALE 1:1 图 数 SHEET 1/1 版 次 REV A

